

SOT569-1

plastic thin fine-pitch ball grid array package; 144 balls; body
12 x 12 x 0.8 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA144
Package type industry code	TFBGA144
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-216
Mounting method type	S (surface mount)
Issue date	14-9-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.8	-	12	12.2	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.74	-	0.8	0.84	mm
n ₂	actual quantity of termination	-	-	144	-	



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2. Package outline

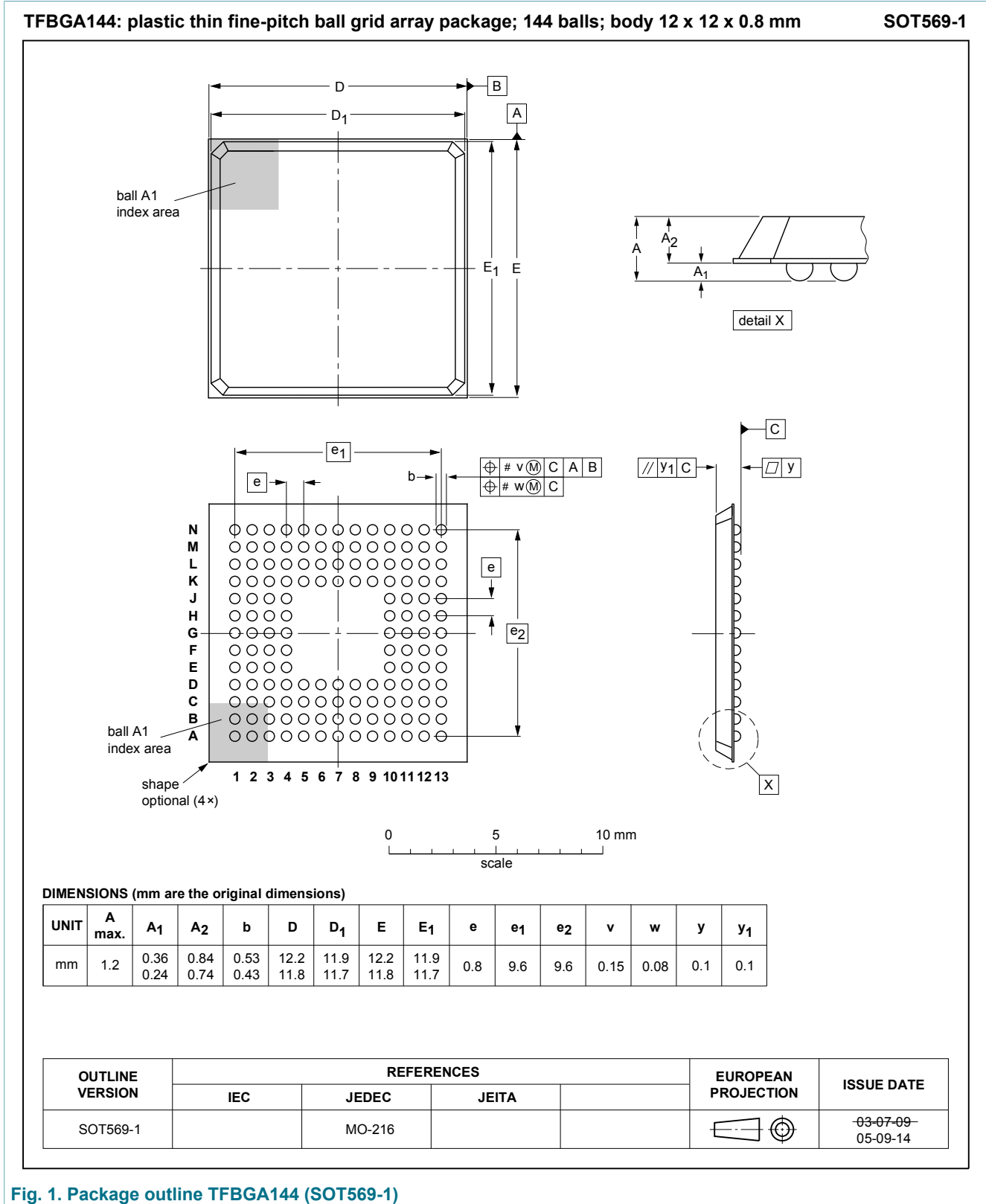
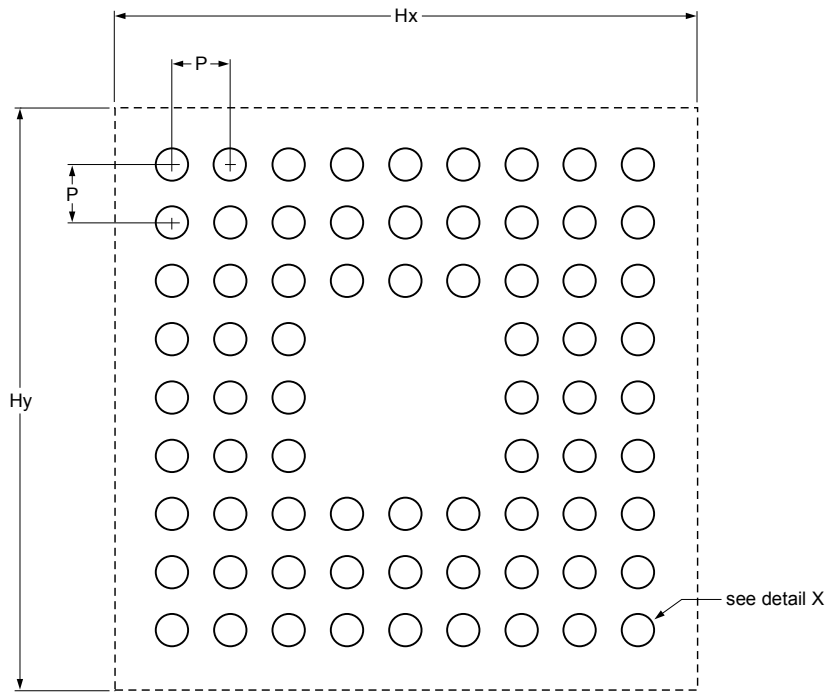


Fig. 1. Package outline TFBGA144 (SOT569-1)

3. Soldering

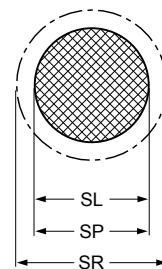
Footprint information for reflow soldering of TFBGA144 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.80	0.400	0.400	0.550	12.575	12.575

sot569-1_fr

Fig. 2. Reflow soldering footprint for TFBGA144 (SOT569-1)

4. Legal information

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